



Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information		*: Required Field

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2024-11-22
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	Antonella Lanzafame	Representative title	APMSMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty statement

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Legal statement

Supplier acceptance* true Legal declaration* Standard

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.



Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
VNH9090AQTR	ESCC*VH95AAM	A	CA2A	2024-11-22
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	150	mg	Each	ECOPACK® 3
Identity	Authority			
Comment	ECOPACK® 3 is STMicroelectronics trade name for ROHS compliant device without use of any ROHS exemption and without Halogen nor Antimony			

Manufacturing information			
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles	
3	260	3	
Bulk solder termination	Terminal plating	Terminal base alloy	Comment
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	0

Package designator	Package size	Number of instances	Shape
QFN	6x6	28	No lead
Comment	BODY QFN 6X6 TRIPLE PAD L26+2		

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	Description

QueryList : ELV directive : 2000/53/EC amended 2020/363_March 2020	Response
1 - Product(s) meets EU ELV requirements without any exemptions	true
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Exemption Id.	Description

QueryList : California Prop65 list, dated 17th Nov 2023	Response		
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen	false		
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen	true		
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.023	alloy	153

QueryList :Customer	Response
QUERY	Response

QueryList : Chinese RoHS , references : SJT 11364 – 2014 and GBT 26572 – 2014	Response			
QUERY	Response			
1 - Product(s) requires marking for the presence of restricted substances and must be marked with an Environmental Protection Use Period under China's Measures for Administration of the control of pollution by Electronic Information Products	false			
2 - Product(s) is eligible for marking with the e code under China's Measures for Administration of the control of pollution by Electronic Information Products	false			
Hazardous substance				
Lead (Pb)	Cadmium (Cd)	Mercury (Hg)	Hexavalent Chromium (Cr VI)	PBB & PBDE
0	0	0	0	0

QueryList : REACH-7th November 2024	Response			
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH	true			
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH	true			
CategoryLevel_Name	CategoryLevel_Threshold	Amount in embedded article / Homogeneous material (mg)	Application - article / Homogeneous material	ppm in article /Homogeneous material



QueryList : Responsible metals sourcing	Response
The component is containing at least one of the following metals : Cobalt , Gold , Tantalum , Tin , Tungsten.	true
The following metals are present is the component :	Tin, Tungsten,

QueryList : Korea Chemical Control Act_ 27 Dec 2017 update	Response
The Product does contain at least one of the substances listed in Chemical Control Act	false

QueryList : China GB 33372-2020 Limit standard for volatile organic compounds content in adhesives - 4 March 2020 application date 1st December 2020	Response
The product contains adhesives identified under GB 33372	false

QueryList:Stockholm Convention Persistent Organic Pollutants (POP)	Response
Product is compliant with Annex A, B and C of Stockholm Convention Persistent Organic Pollutants	true

QueryList: EU Ship Recycling Regulation No. 1257/2013	Response
Product contains hazardous materials listed in Annex II of EU Ship Recycling Regulation No.1257/2013 and 2009/16/EC Directive	False

PFAS/PTFE Declaration	Response
The product is containing at least one of the following PFAS substance: Polytetrafluoroethylene,Thiophenium, Triphenylsulfonium nonaflate, Trifluoroacetic anhydride	False

BPA Declaration	Response
Product does not contain Bisphenol A (Isopropylidenediphenol)	True

Montreal Protocol	Response
Product does not contain Ozone Depleting Substances based on Annex I to Annex VII of EU REGULATION (EC) No 1005/2009	True

Environmental Protection Agency:Toxic Substances Control Act (TSCA). Section 6(h)	Response
Product does not contain Phenol, isopropylated, phosphate (3:1)	True

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	ESCC-VH95AAM		150.0000		6999999.0	999997.0				
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Dies	M-011 Other inorganic materials	1.823	mg	supplier	die	Silicon(Si)	7440-21-3		1.520	mg	833790	10133				
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.060	mg	32913	400				
				supplier	metallisation	Copper(Cu)	7440-50-8		0.027	mg	14811	180				
				supplier	metallisation	Nickel(Ni)	7440-02-0		0.023	mg	12617	153				
				supplier	metallisation	Silver(Ag)	7440-22-4		0.009	mg	4937	60				
				supplier	metallisation	Titanium(Ti)	7440-32-6		0.008	mg	4388	53				
				supplier	metallisation	Tungsten(W)	7440-33-7		0.107	mg	58694	713				
				supplier	metallisation	Vanadium(V)	7440-62-2		0.002	mg	1097	13				
				supplier	Passivation	Silicon nitride(SiN)	12033-89-5		0.010	mg	5485	67				
				supplier	passivation	Silicon oxide	7631-86-9		0.047	mg	25782	313				
				supplier	polymer coating	polyimide	proprietary		0.010	mg	5485	67				
				Leadframe	M-004 Copper and its alloys	43.038	mg	supplier	alloy	Copper(Cu)	7440-50-8		40.664	mg	944839	271093
								supplier	alloy	Iron (Fe)	7439-89-6		0.716	mg	16636	4773
supplier	alloy	Iron phosphide	26508-33-8						0.166	mg	3857	1107				
supplier	alloy	Zinc(Zn)	7440-66-6						0.053	mg	1231	353				
supplier	metallization	Silver(Ag)	7440-22-4						1.439	mg	33436	9593				
Die attach	M-011 Other inorganic materials	0.646	mg	supplier	glue	Silver(Ag)	7440-22-4		0.559	mg	865325	3727				
				supplier	glue	phenolic Resin	9003-35-4		0.029	mg	44892	193				
				supplier	glue	Hexanediol diglycidyl ether	16096-31-4		0.029	mg	44892	193				
				supplier	glue	Bisphenol F type epoxy resin	9003-36-5		0.003	mg	4644	20				
				supplier	glue	Epoxy Cresol Novolak	29690-62-2		0.023	mg	35604	153				
				supplier	glue	Epoxyde bisphenol A resin	25068-38-6		0.003	mg	4644	20				
Bonding wires	M-004 Copper and its alloys	1.131	mg	supplier	wire	Copper(Cu)	7440-50-8		1.131	mg	1000000	7540				
Bonding wires 2	M-004 Copper and its alloys	0.212	mg	supplier	wire	Copper(Cu)	7440-50-8		0.212	mg	1000000	1413				
Encapsulation	M-011 Other inorganic materials	102.085	mg	supplier	mold compound	Silica vitreous	60676-86-0		89.835	mg	880002	598900				
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		5.104	mg	49998	34027				
				supplier	mold compound	Phenolic resin	205830-20-2		3.981	mg	38997	26540				
				supplier	mold compound	Epoxy type resin	proprietary		2.042	mg	20003	13613				
				supplier	mold compound	Carbon black	1333-86-4		0.204	mg	1998	1360				
				supplier	mold compound	other	proprietary		0.919	mg	9002	6127				
Connections coating	Solder	1.065	mg	supplier	solder alloy	Tin(Sn)	7440-31-5		1.065	mg	1000000	7100				